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RESPONSE UNDER 37 CFR 1.116  
EXPEDITED PROCEDURE

IN THE U.S. PATENT AND TRADEMARK OFFICE

January 16, 2009

Applicants: Atsushi YABE et al

For: ELECTROLESS COPPER PLATING SOLUTION AND  
ELECTROLESS COPPER PLATING METHOD

Serial No.: 10/576 230

Group: 1792

Confirmation No.: 7180

Filed: April 14, 2006

Examiner: Bareford

International Application No.: PCT/JP2004/014049

International Filing Date: September 17, 2004

Atty. Docket No.: 4700.P0328US

Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

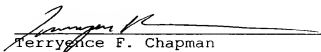
**AMENDMENT AFTER FINAL REJECTION**

Sir:

In response to the Office Action dated October 20, 2008,  
please amend the above-identified application as follows:  
(Please see following pages.)

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**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being  
deposited with the United States Postal Service with  
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Alexandria, VA 22313-1450, on January 16, 2009.

  
Terrynece F. Chapman